

FIG. 1 (PRIOR ART)

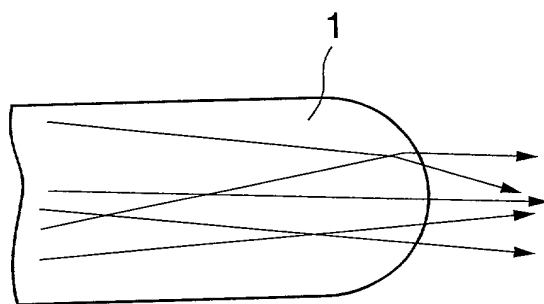


FIG. 2 (PRIOR ART)

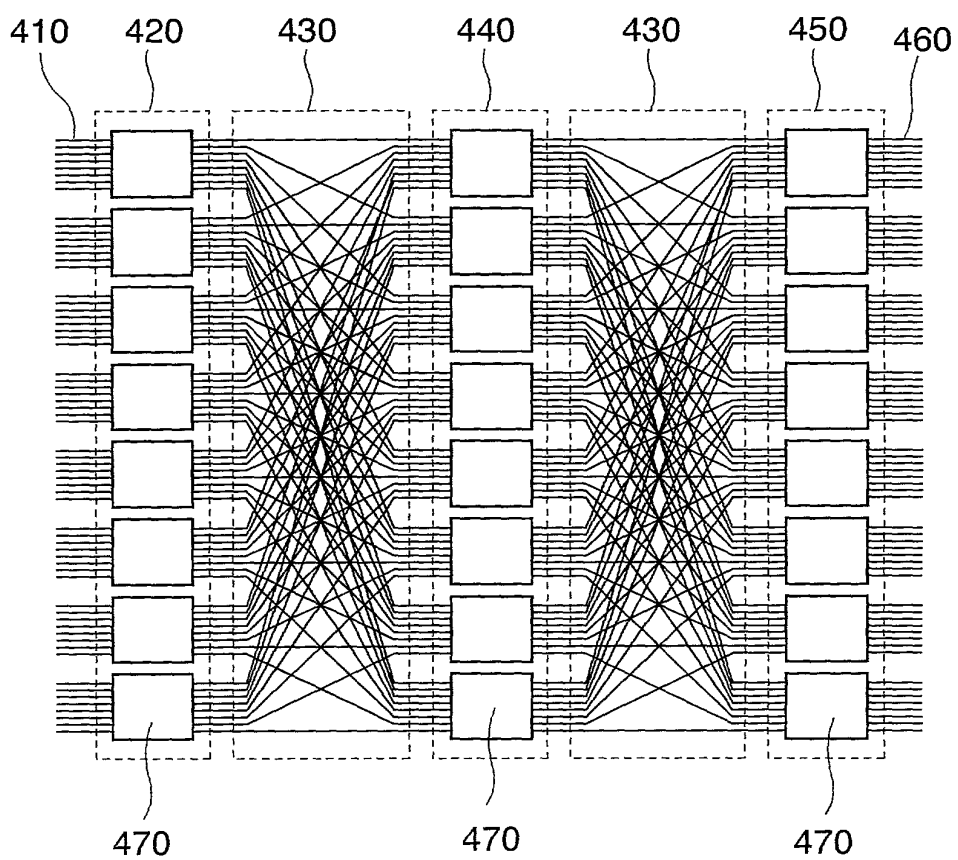


FIG. 3A
(PRIOR ART)

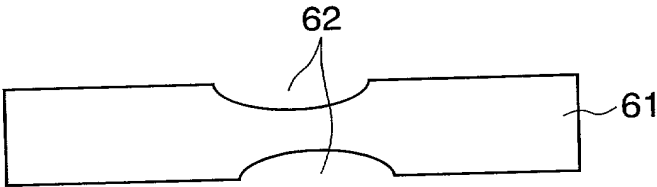


FIG. 3B
(PRIOR ART)

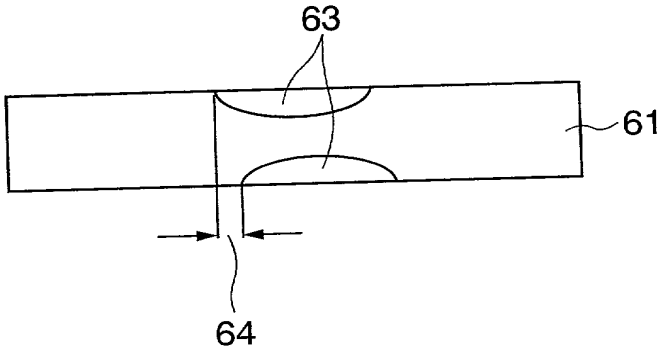


FIG. 4 (PRIOR ART)

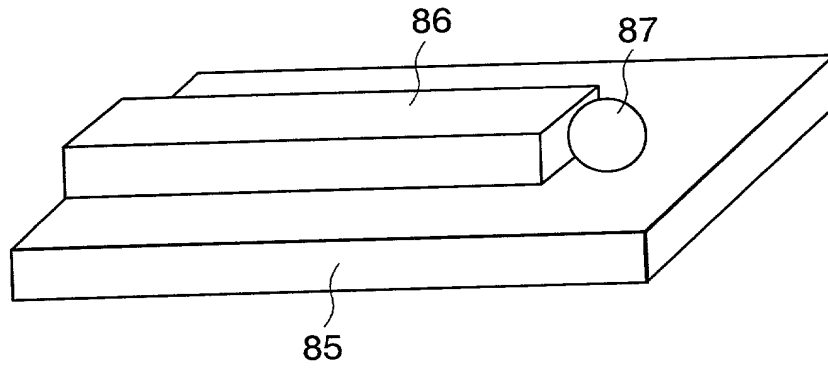


FIG. 5 (PRIOR ART)

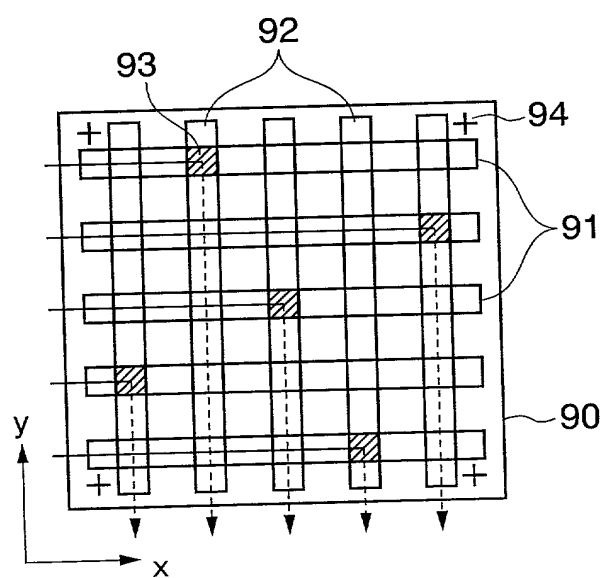


FIG. 6 (PRIOR ART)

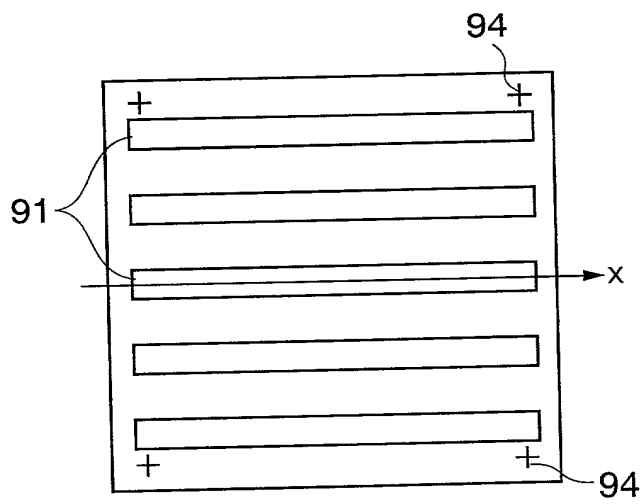


FIG. 7 (PRIOR ART)

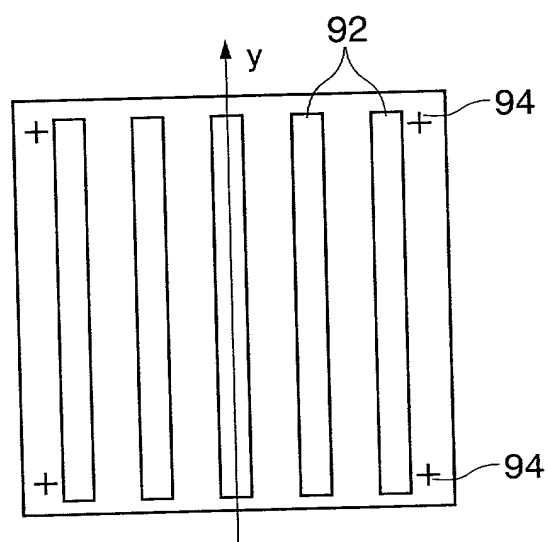


FIG. 9

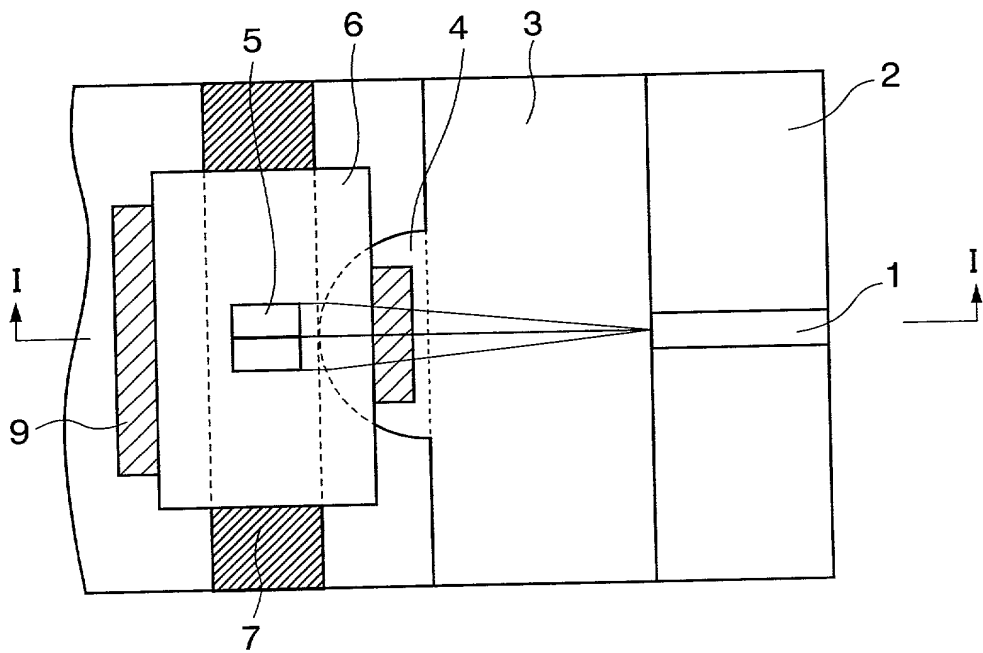


FIG. 10

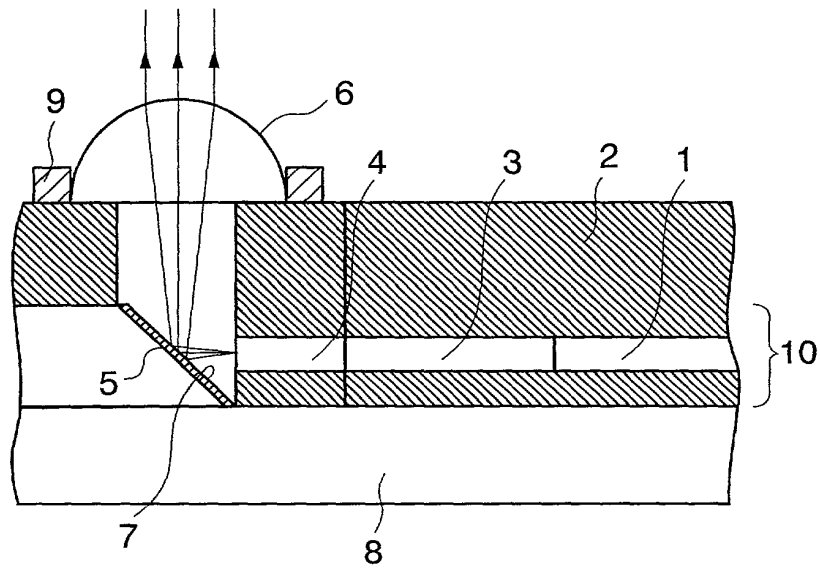


FIG. 11

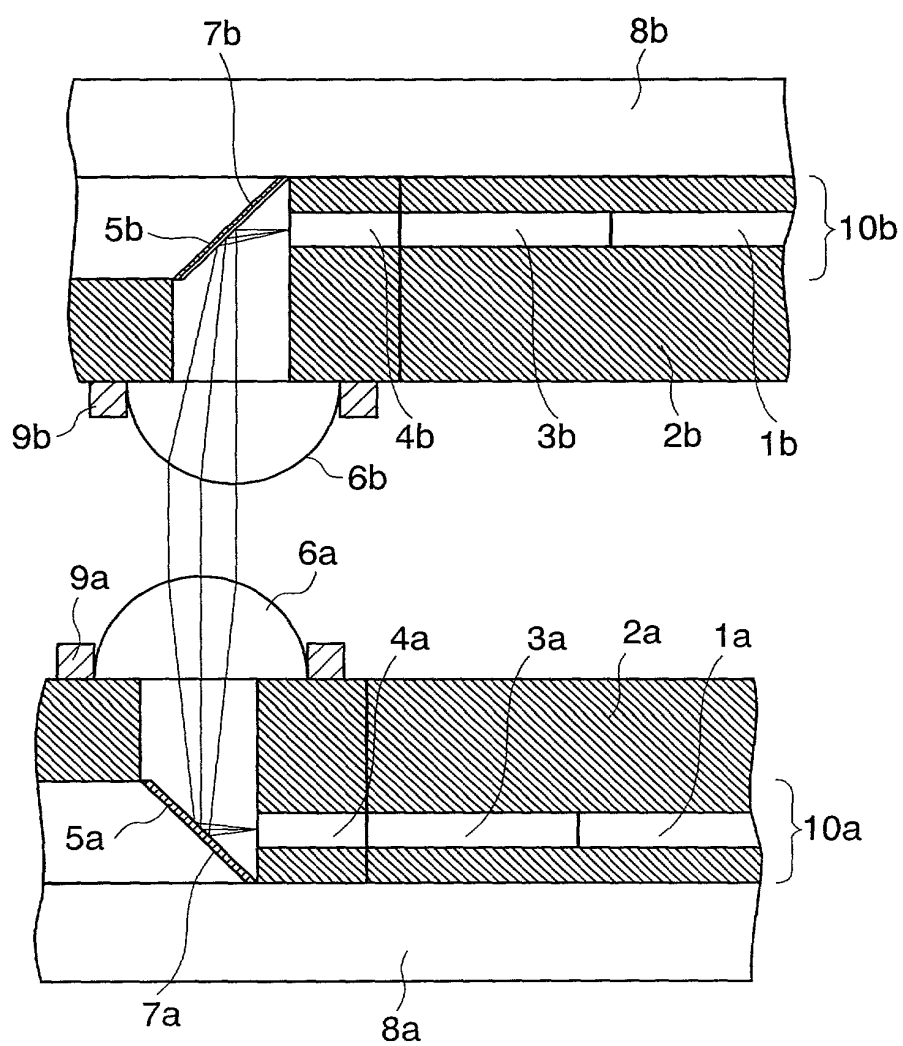


FIG. 12

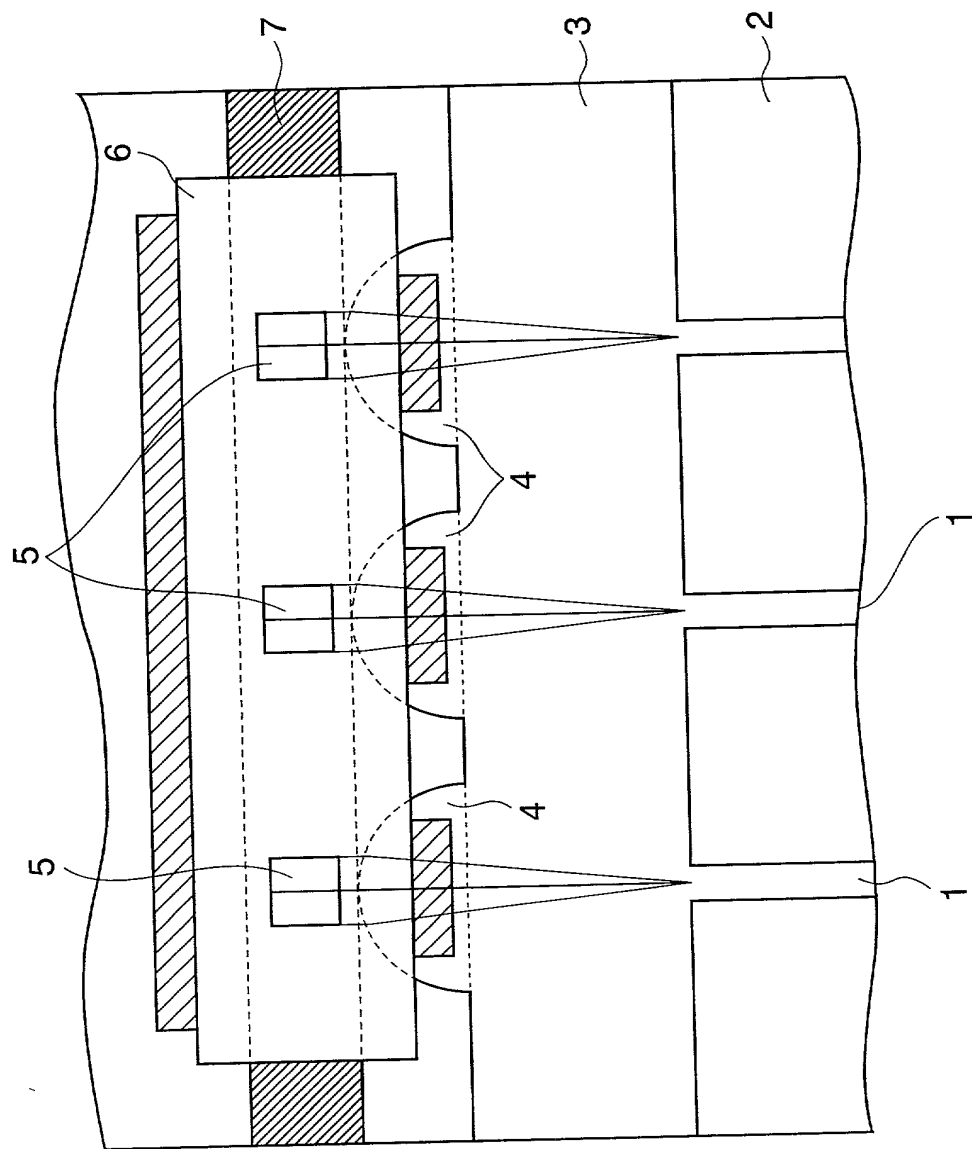


FIG. 13

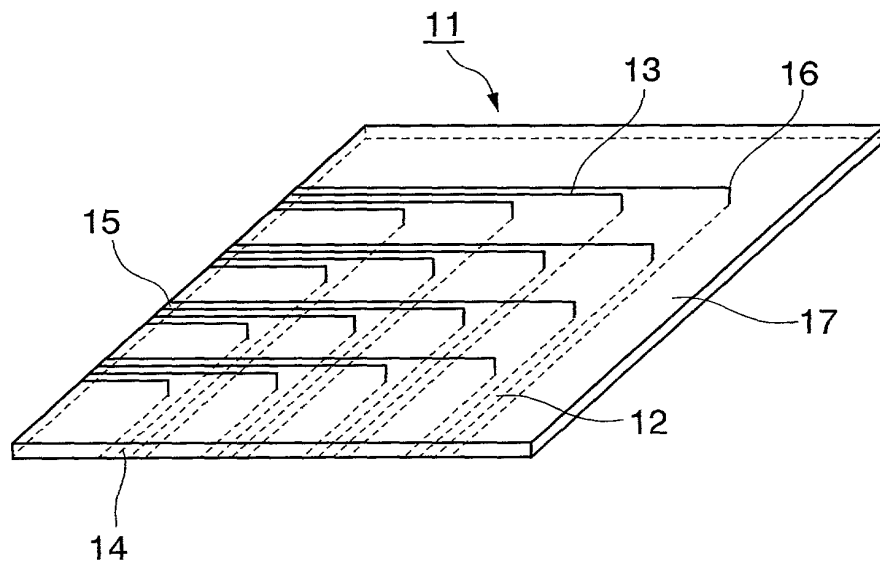


FIG. 14

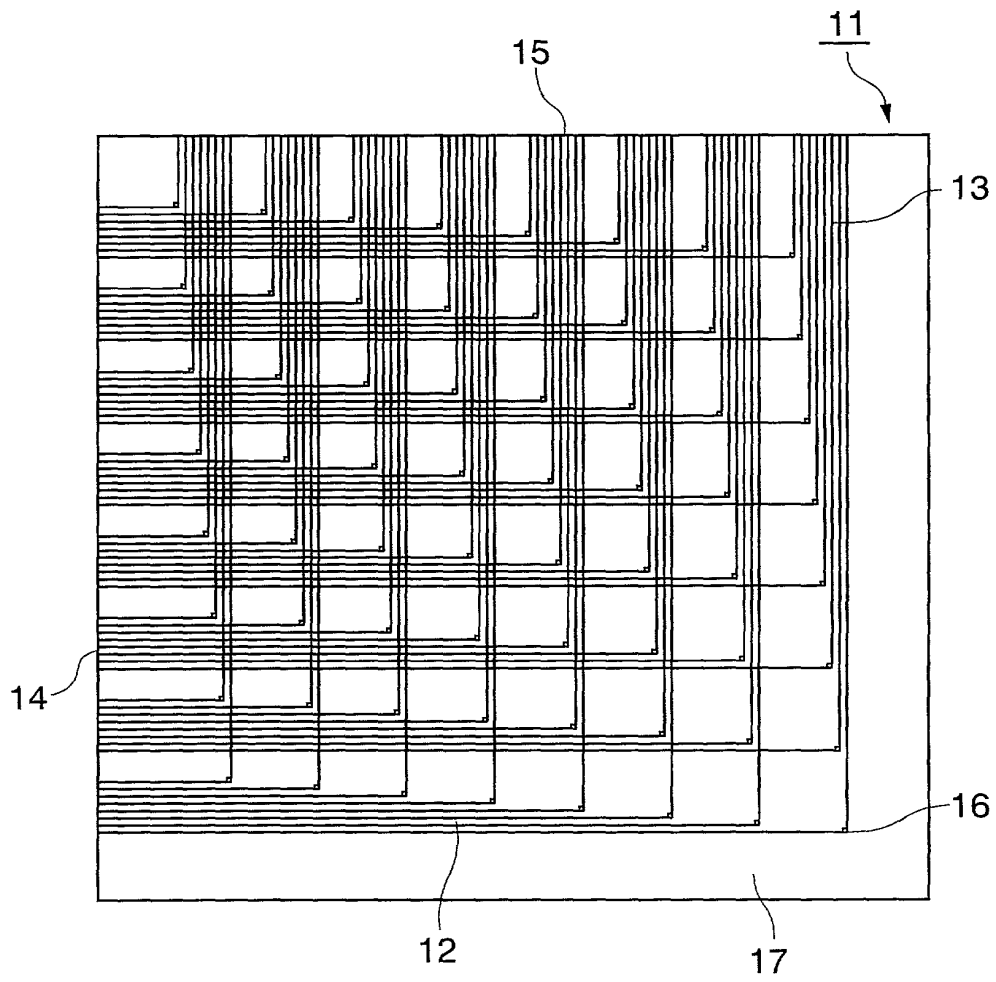
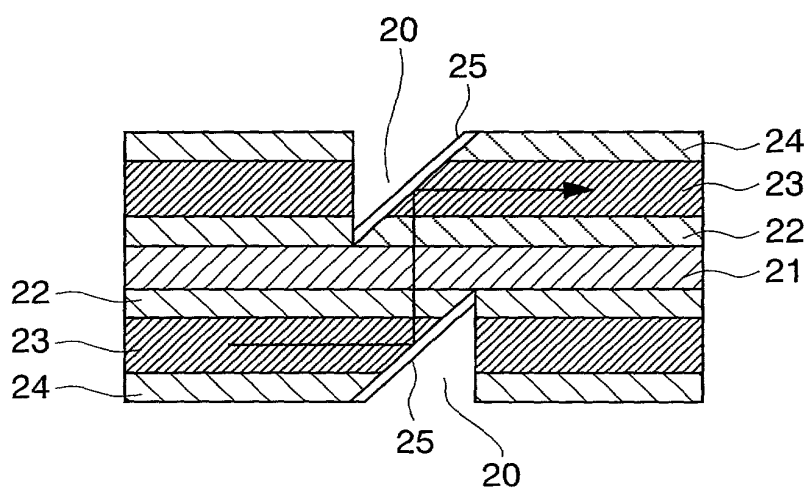


FIG. 15



2025 RELEASE UNDER E.O. 14176

FIG. 16A

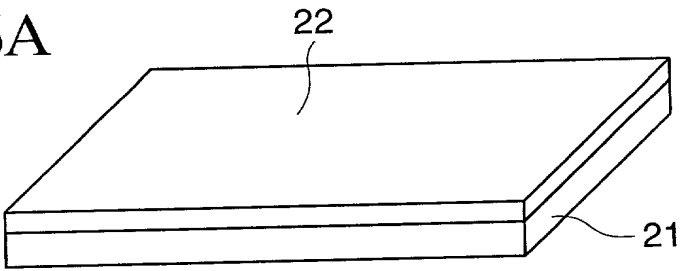


FIG. 16B

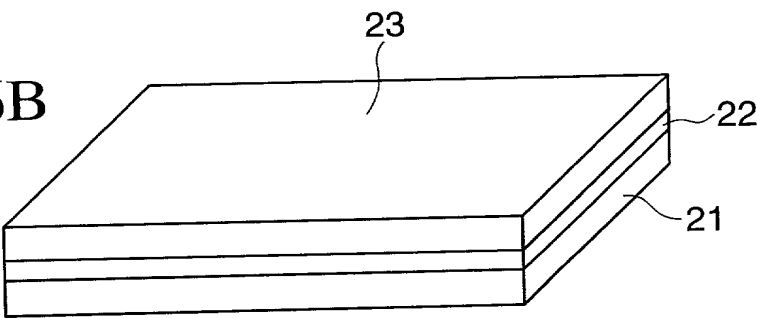


FIG. 16C

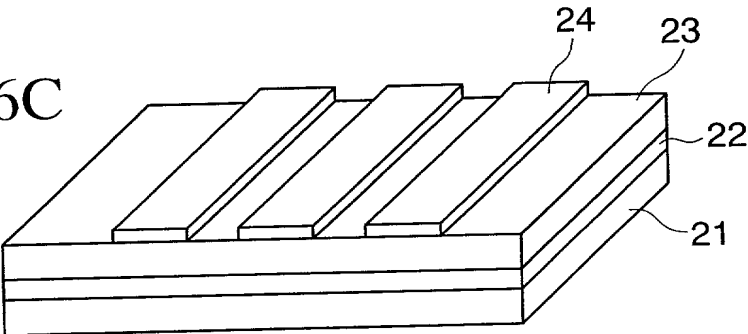


FIG. 16D

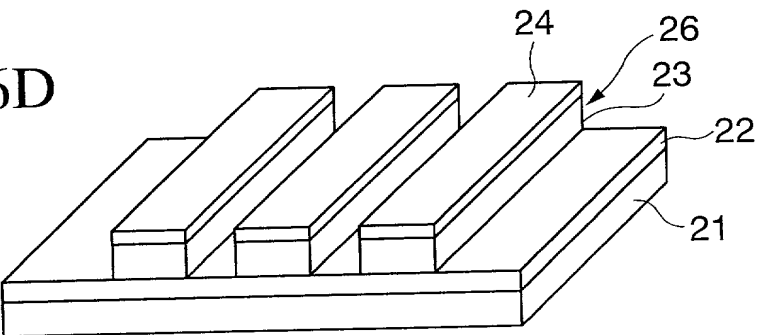


FIG. 16E

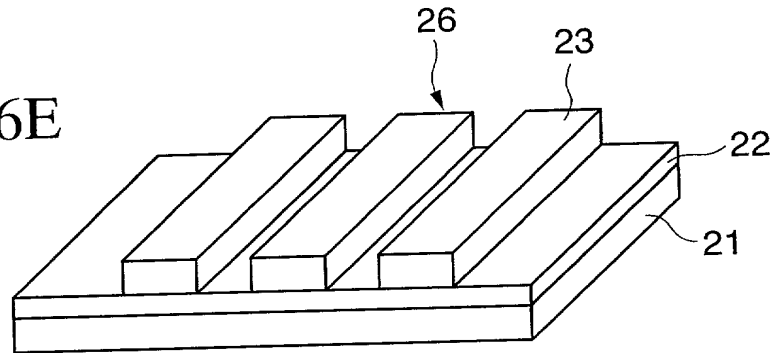


FIG. 16F

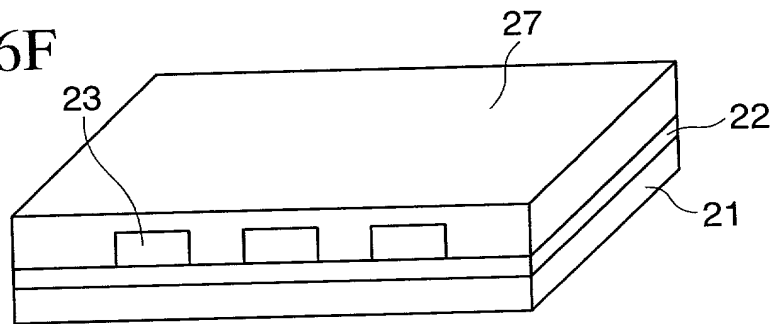


FIG. 16G

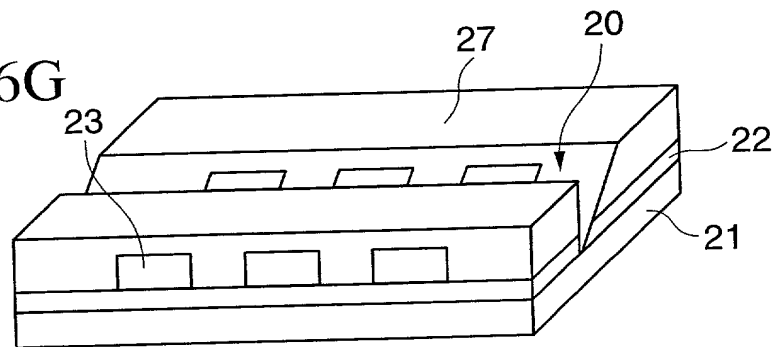


FIG. 16H

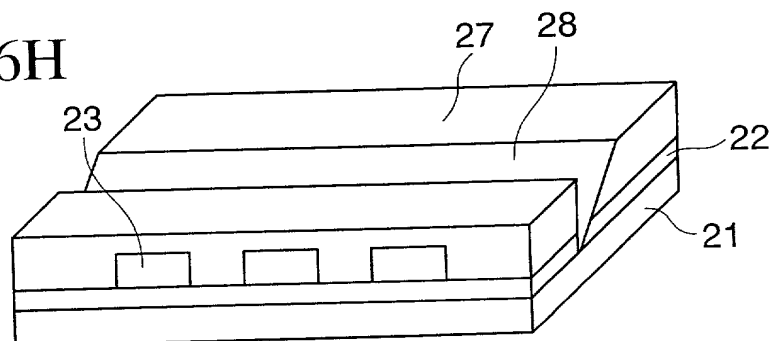


FIG. 17

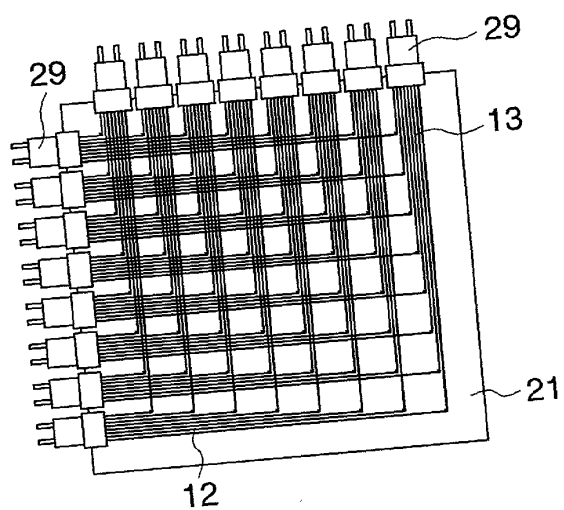
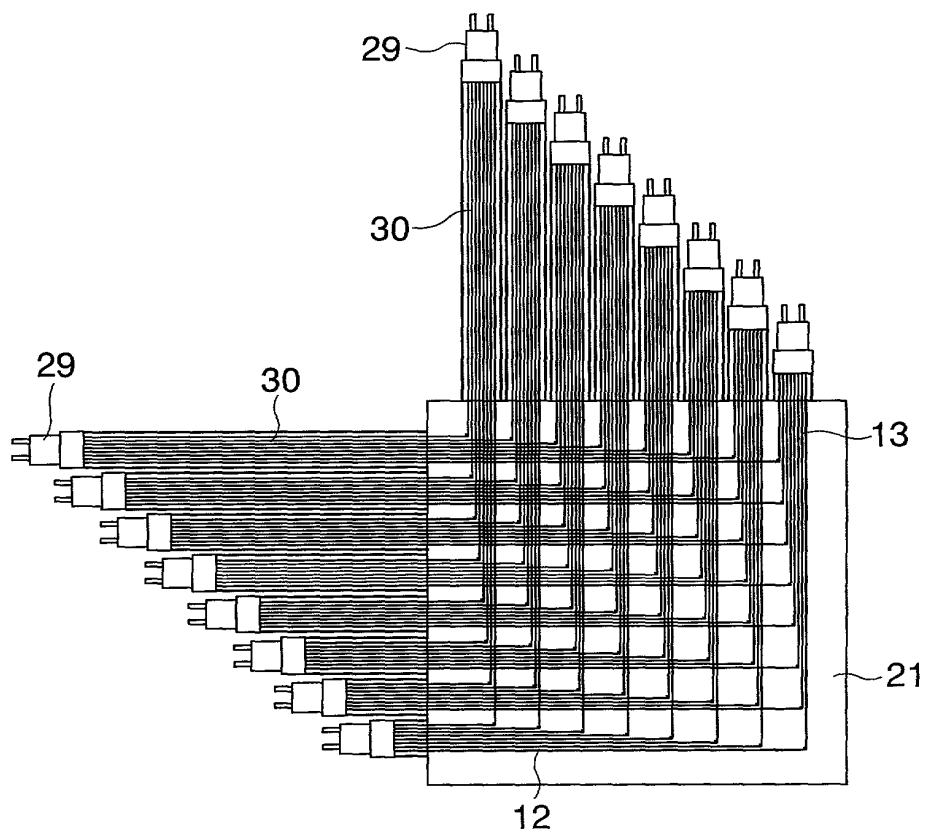


FIG. 18



THE UNIVERSITY OF CHICAGO

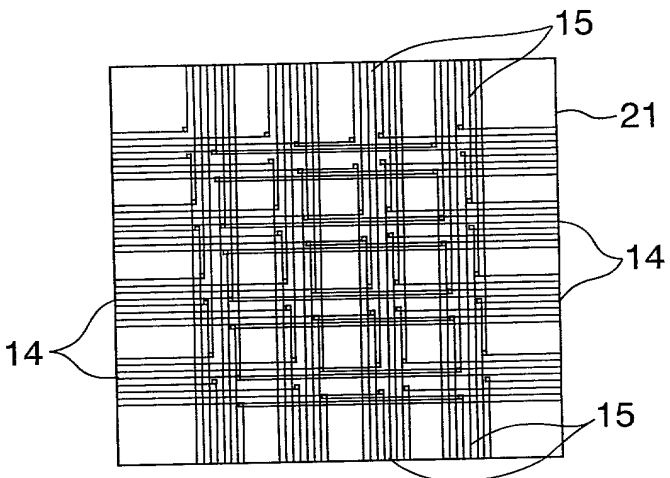


FIG. 19B

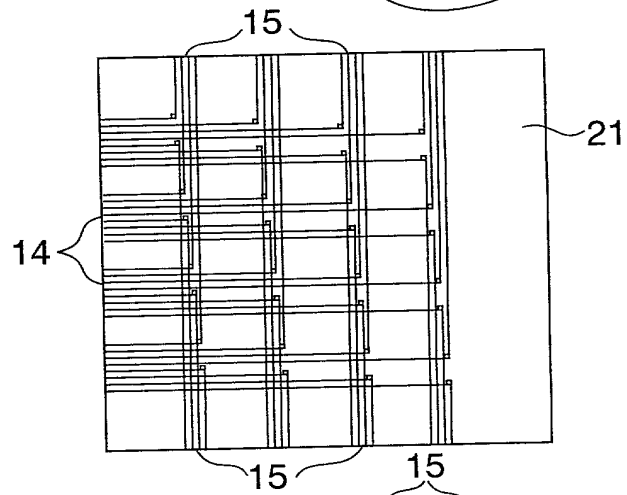


FIG. 19C

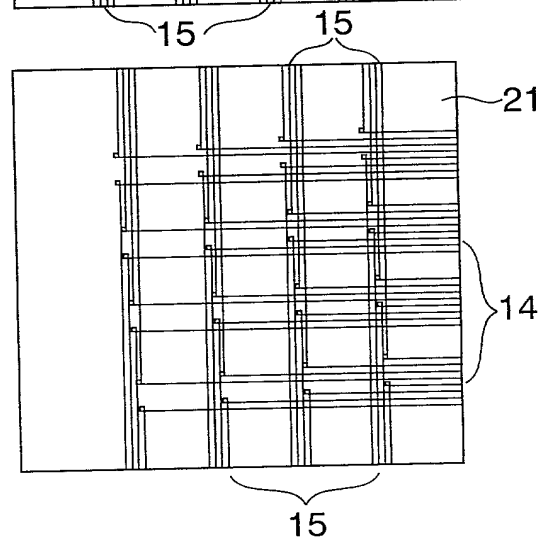


FIG. 20

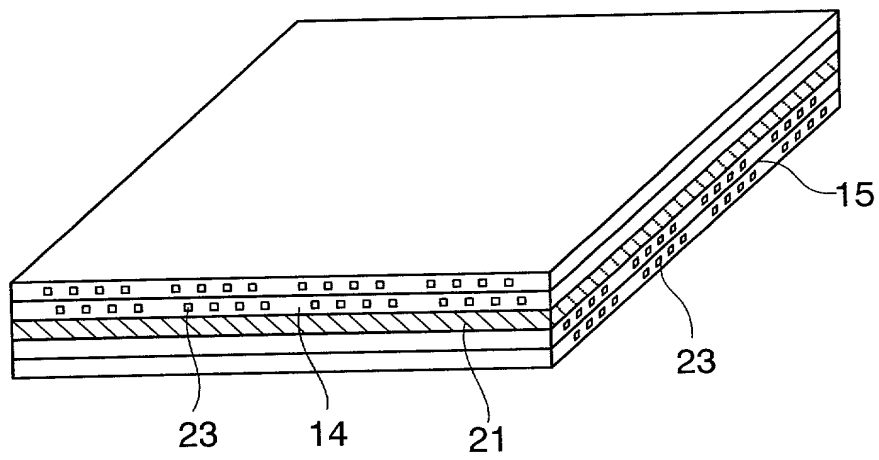


FIG. 21

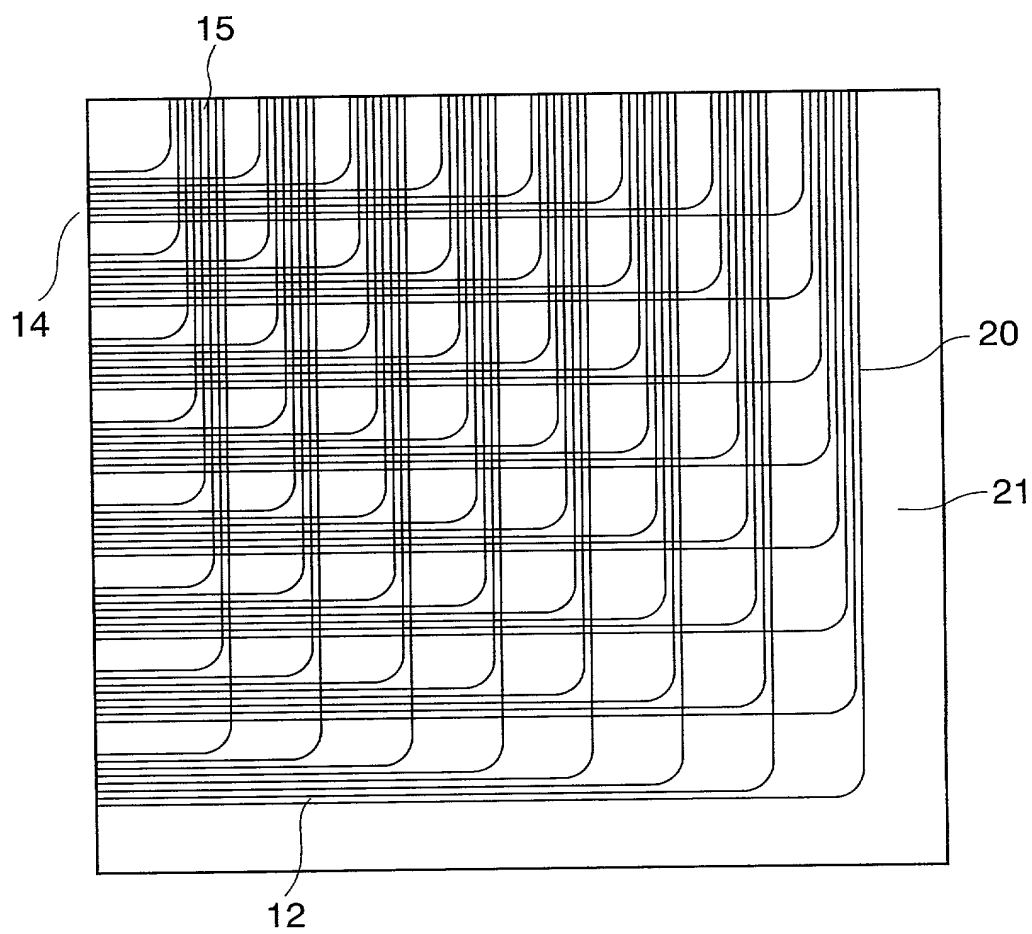


FIG. 22A

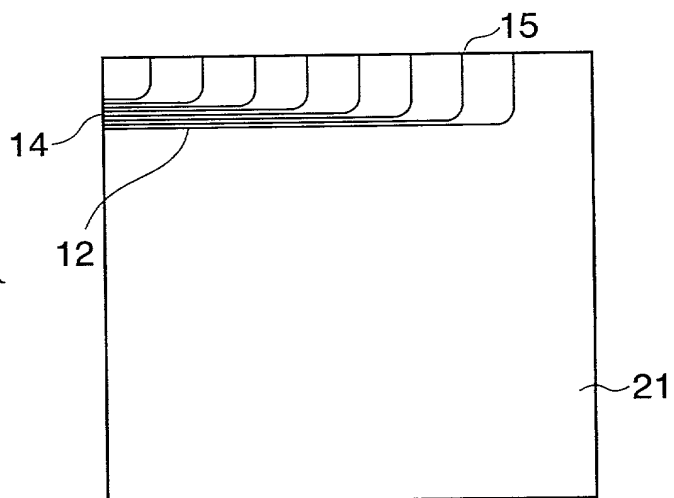


FIG. 22B

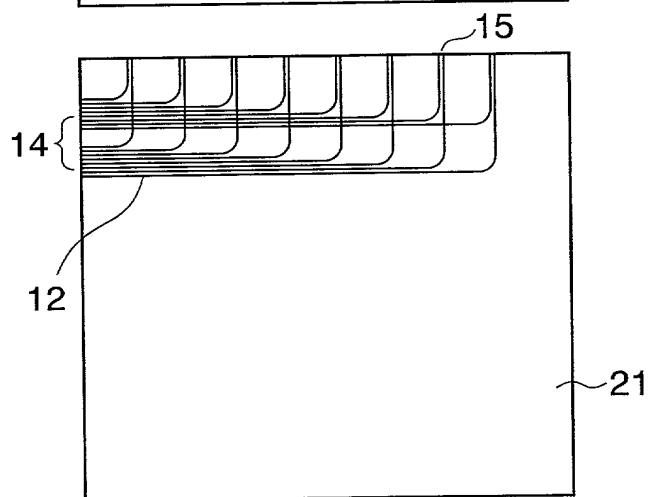


FIG. 22C

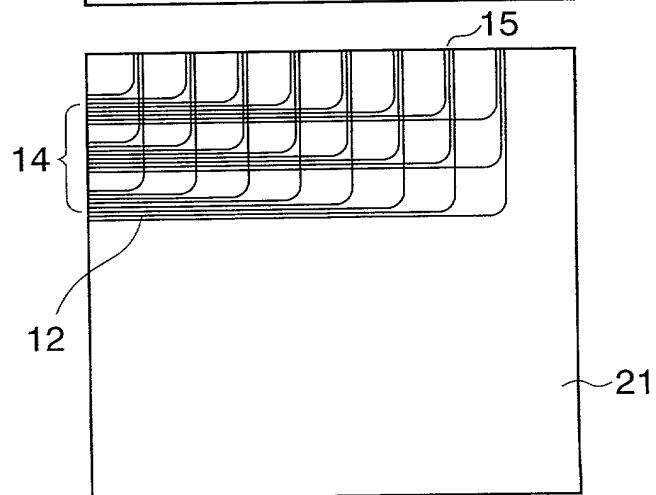


FIG. 23

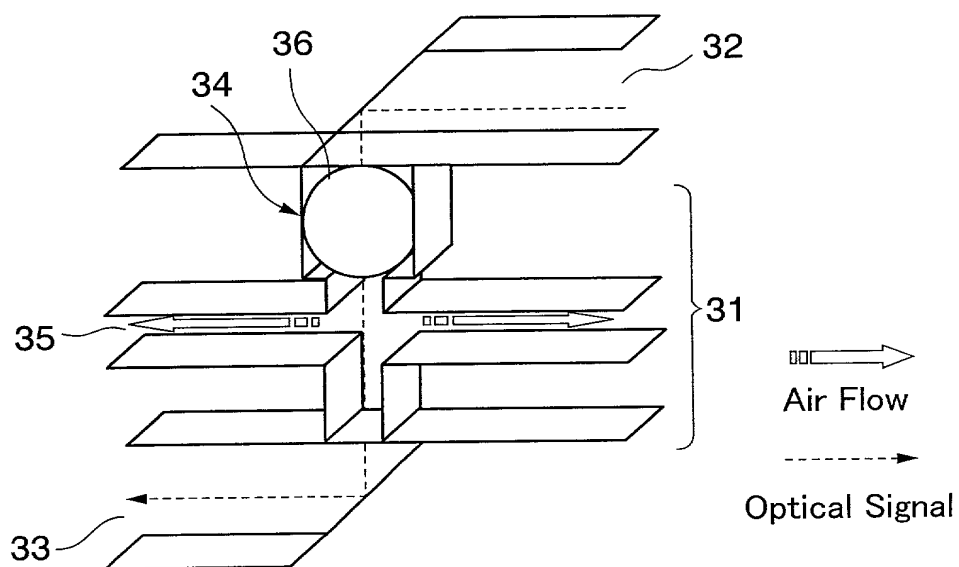


FIG. 24

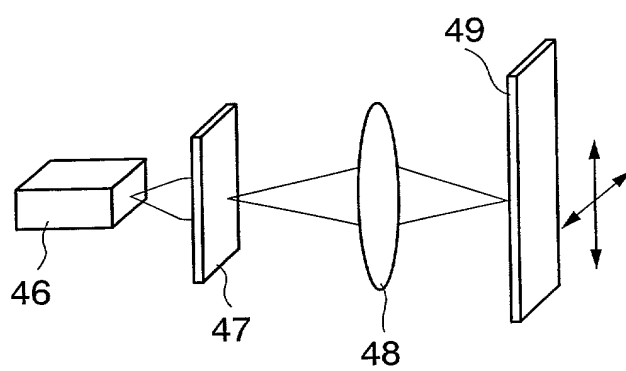


FIG. 25

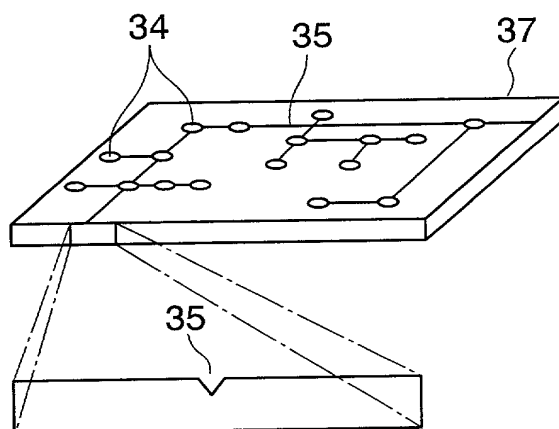


FIG. 26

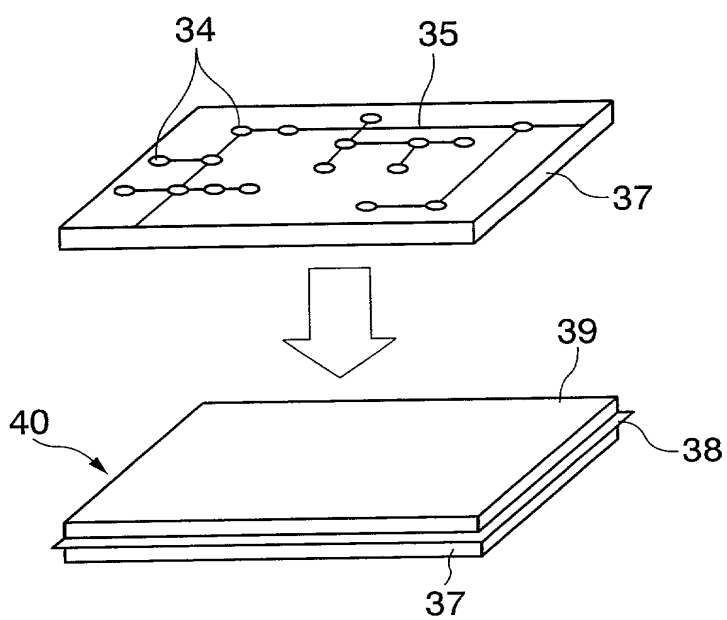


FIG. 27

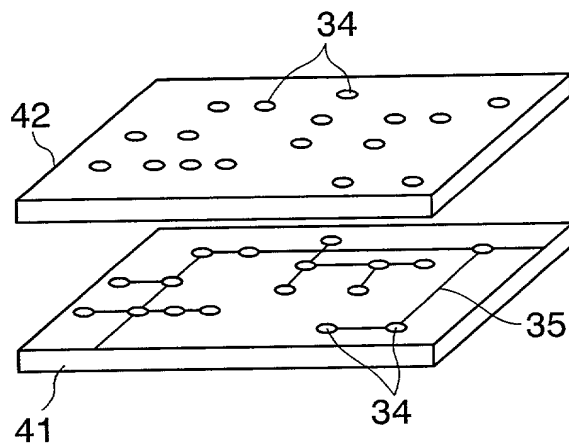


FIG. 28

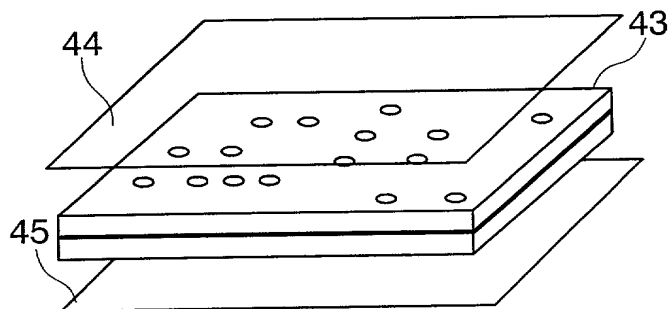


FIG. 29

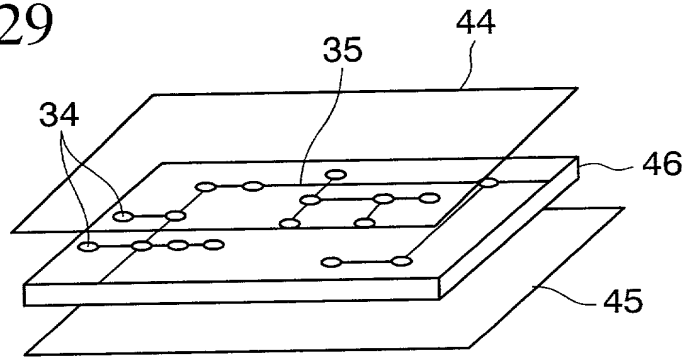


FIG. 30

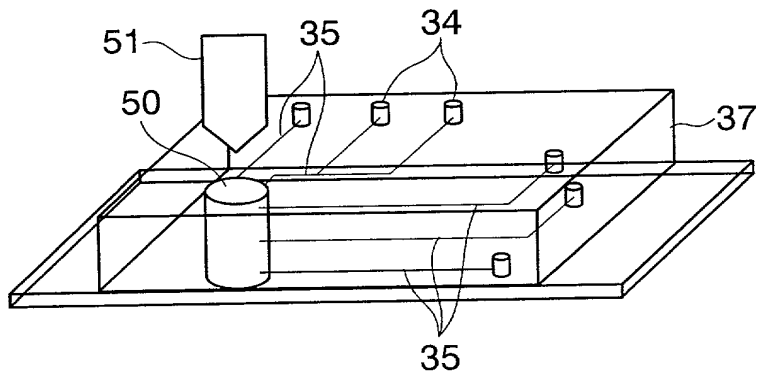


FIG. 31

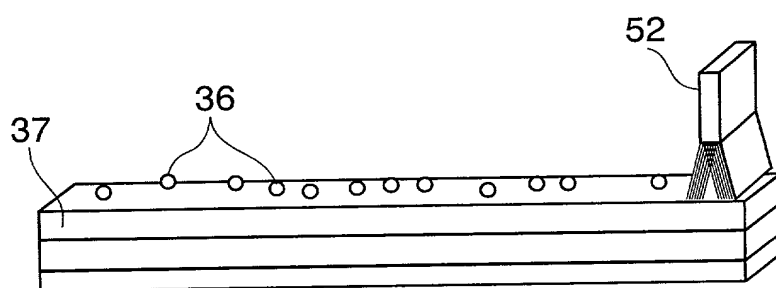


FIG. 33

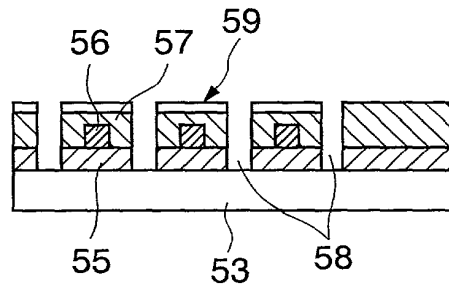


FIG. 34

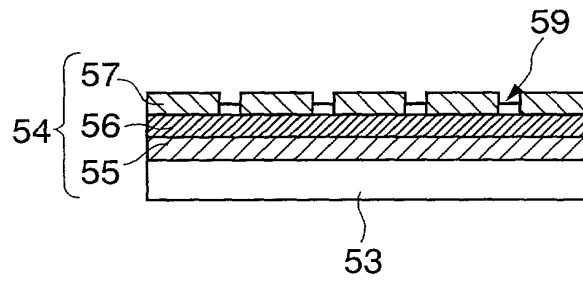
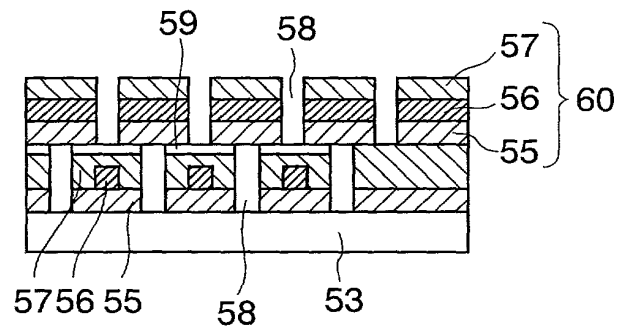


FIG. 35



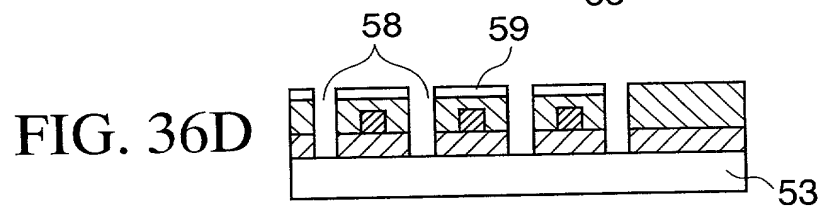
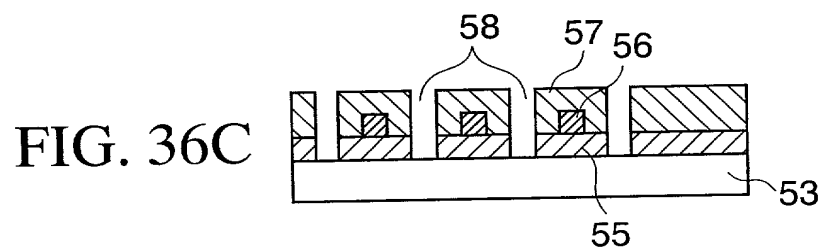
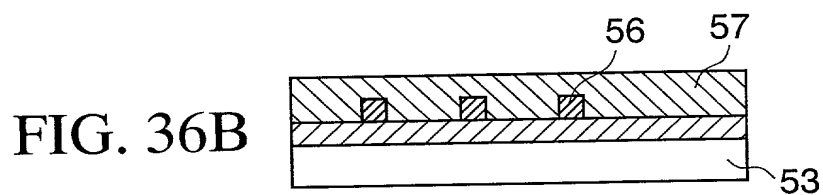
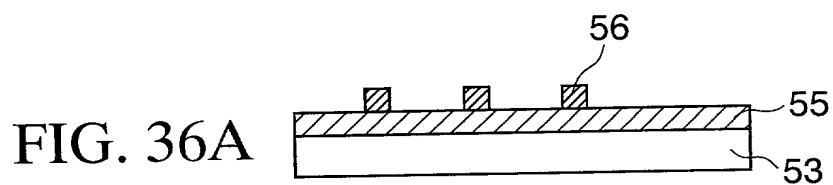
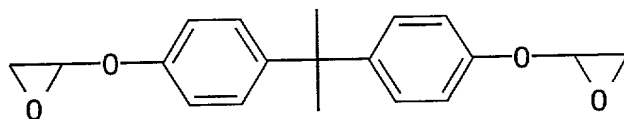
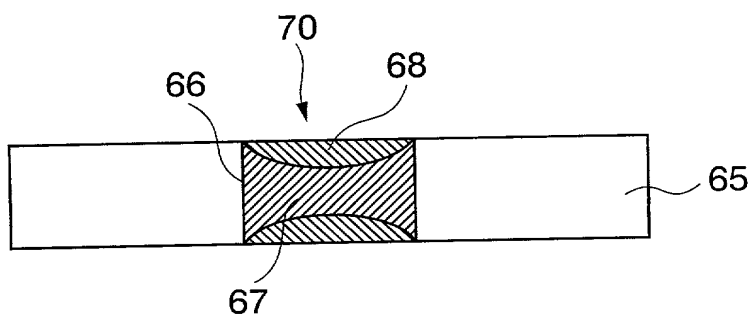


FIG. 37



1 Bisphenol A Diglycidyl

FIG. 38



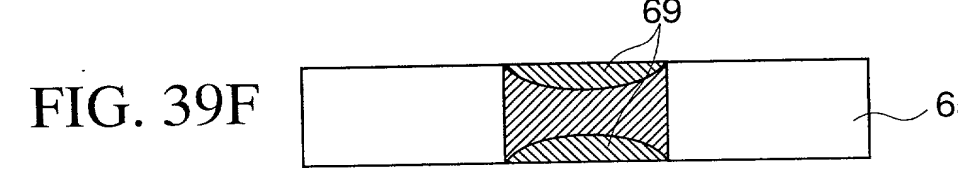
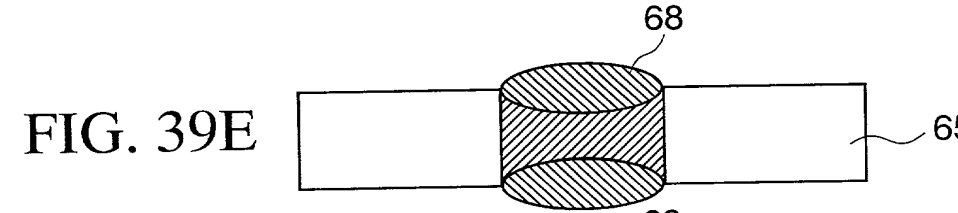
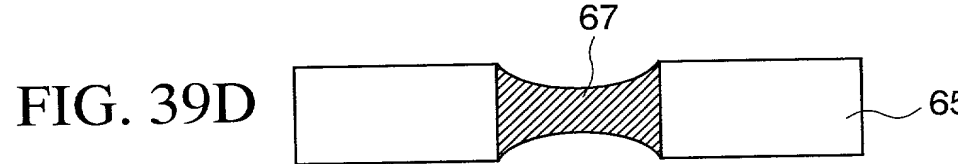
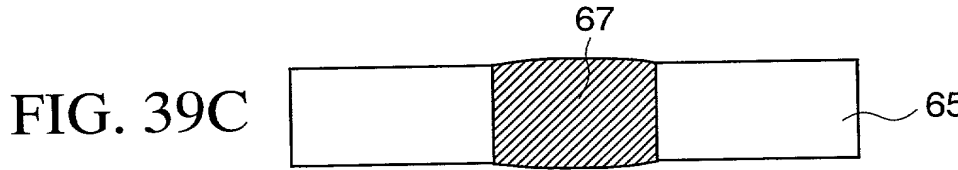
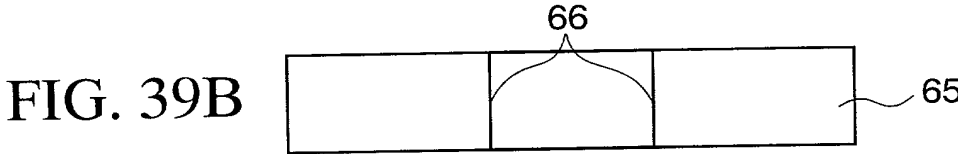


FIG. 40

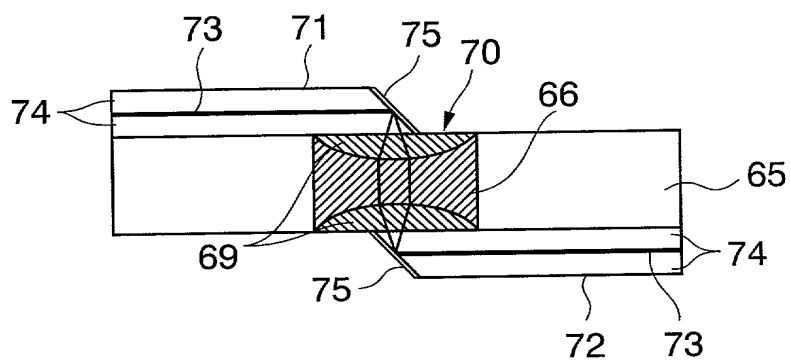


FIG. 41A

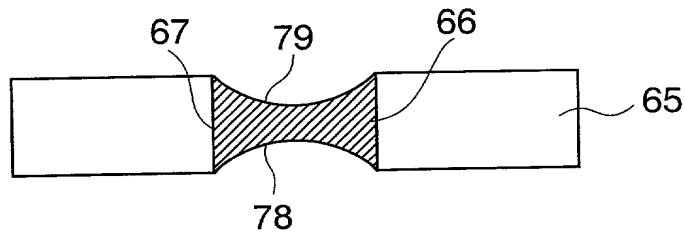


FIG. 41B

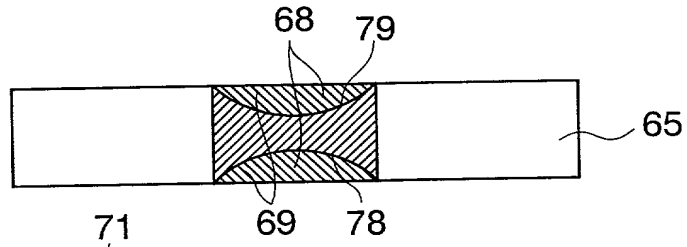
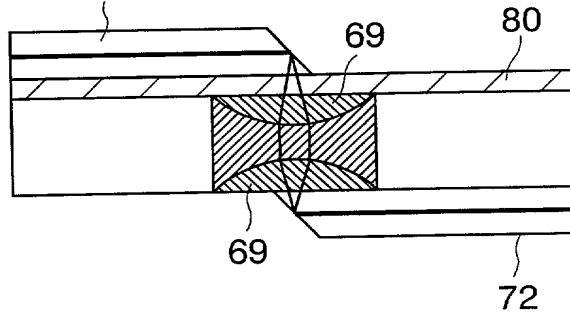
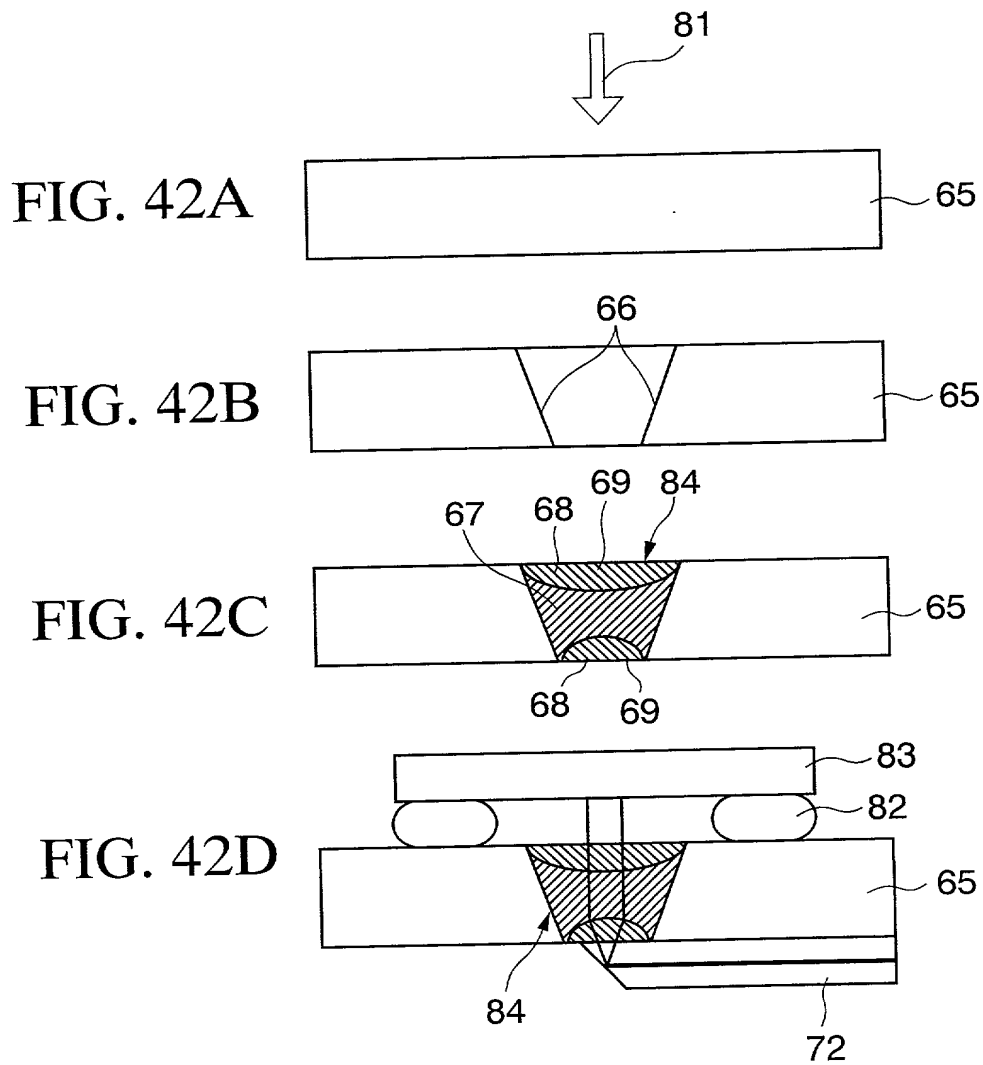


FIG. 41C





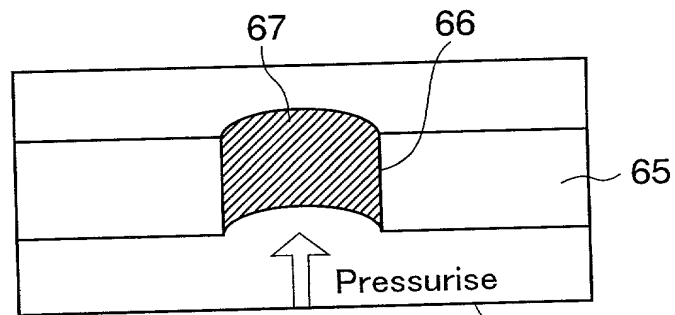


FIG. 44

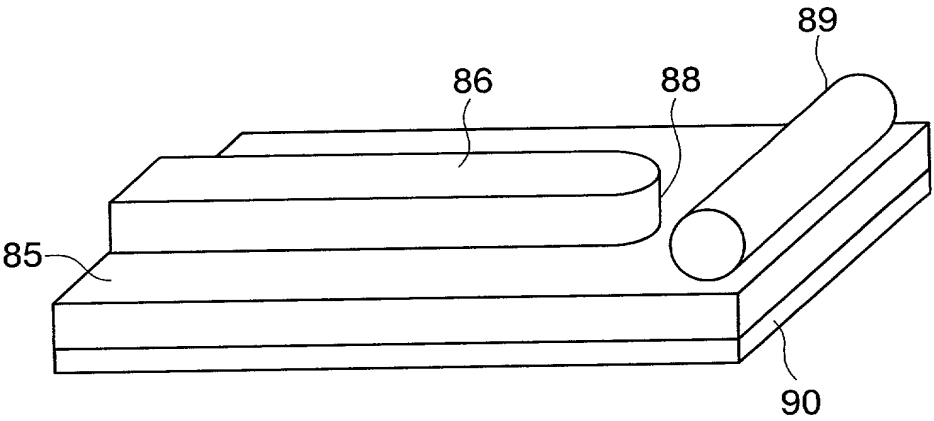


FIG. 45

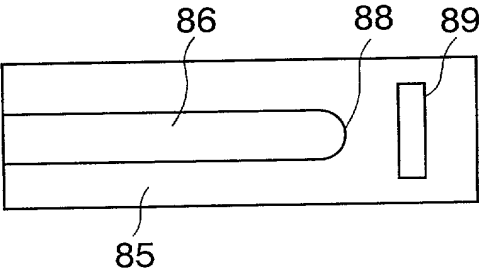


FIG. 46

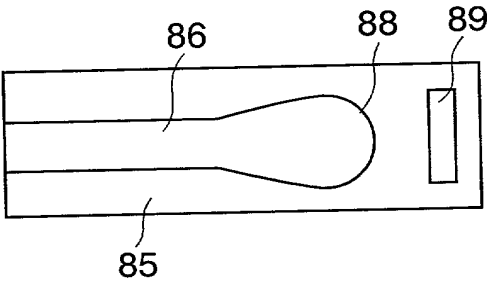


FIG. 47

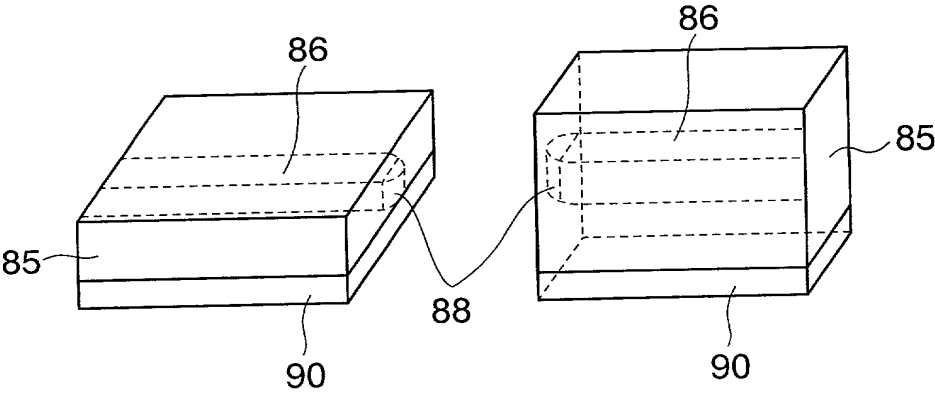


FIG. 48

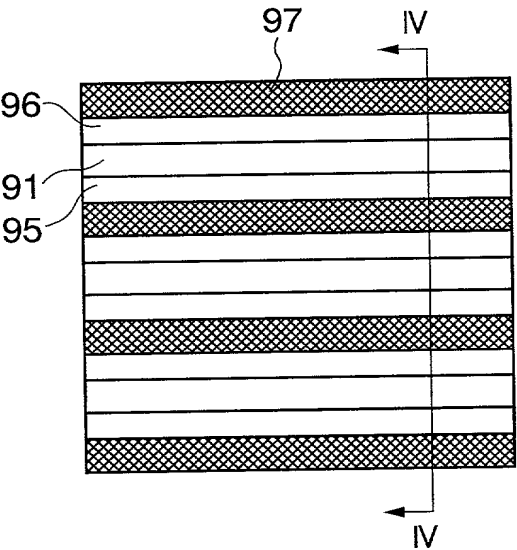


FIG. 49

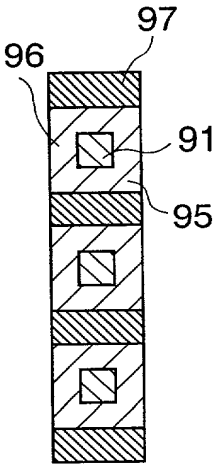


FIG. 50

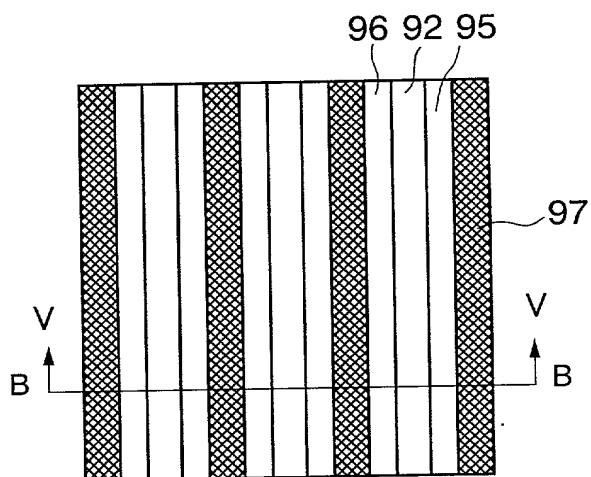
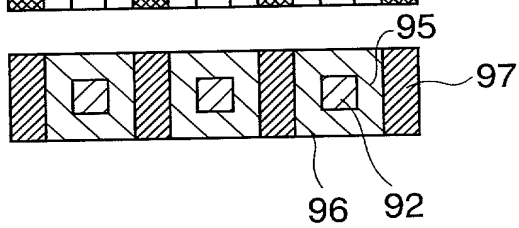


FIG. 51





A cross-sectional view of a semiconductor device. It shows a substrate 98 with a layer 95 on top. Layer 95 has a patterned layer 96 on its surface, which contains three openings 92. The openings 92 are rectangular and are filled with a material, possibly a conductive paste or solder, which is shown with a diagonal hatching pattern. The layer 96 is shown with a wavy, undulating surface between the openings.

A cross-sectional view of a semiconductor device. It shows a substrate 98 at the bottom, followed by a layer 95. Above layer 95 is a patterned layer 96 with openings 92. The top surface of the device is labeled 97.

FIG. 56

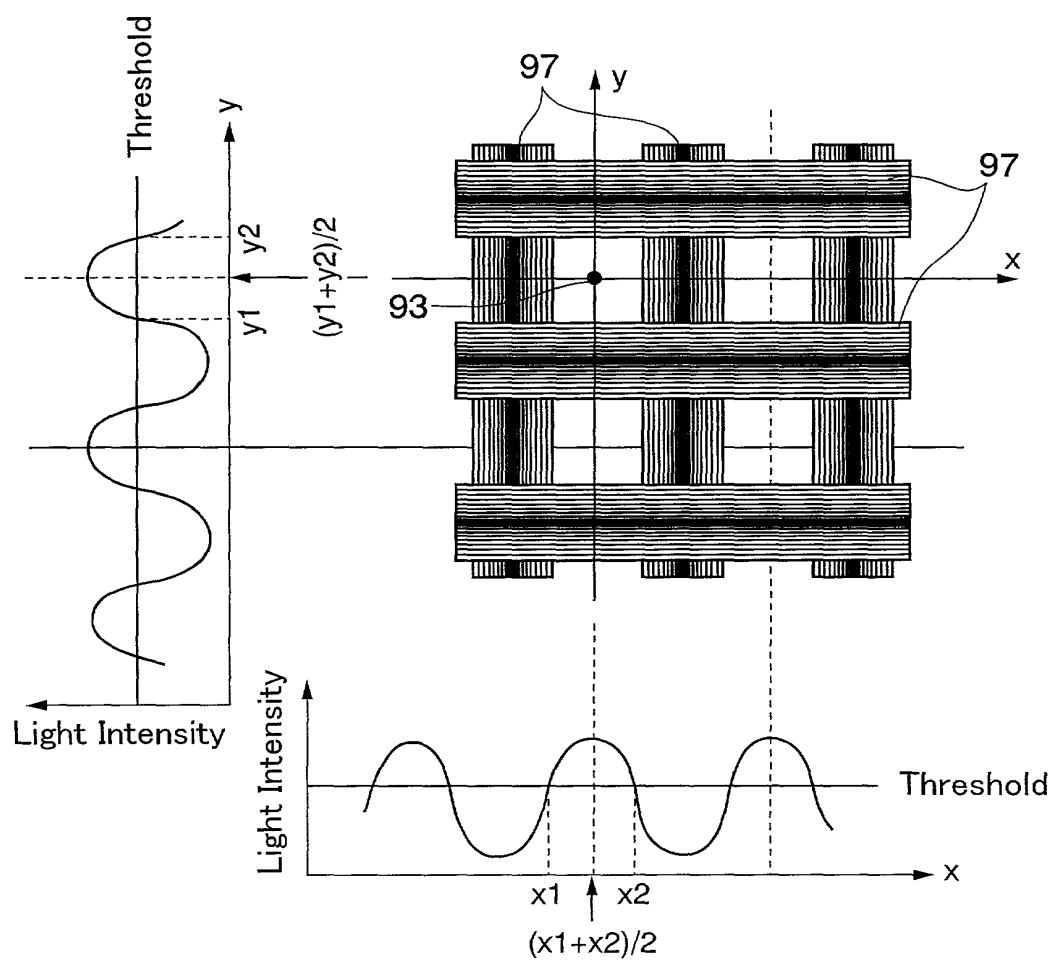


FIG. 57

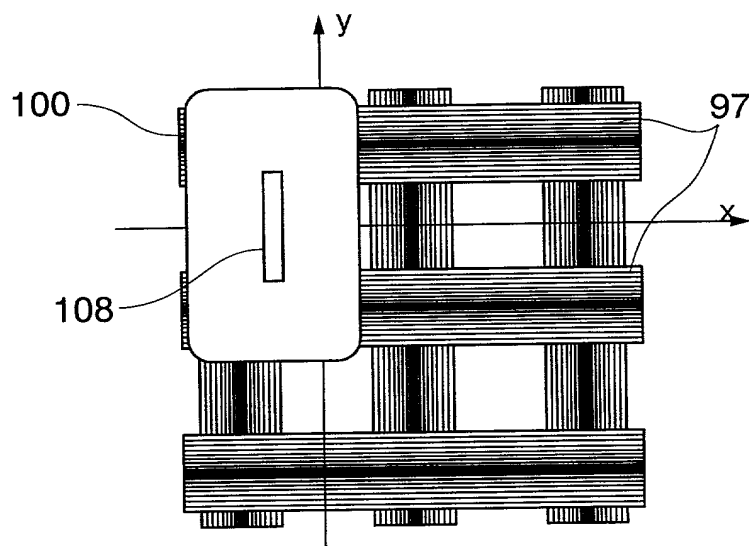


FIG. 58

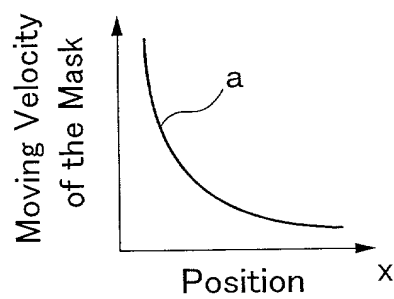


FIG. 59

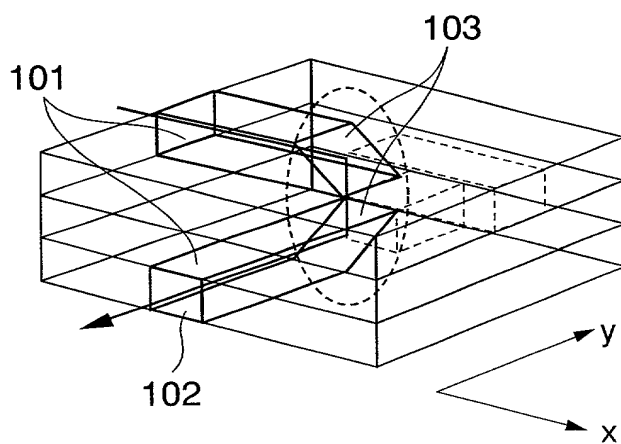




FIG. 62

